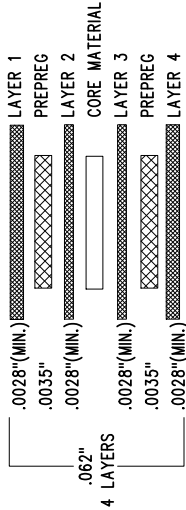


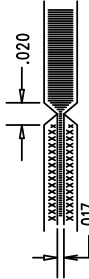
REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	2	PRODUCTION	N.HARA
			4-05-23

LAYER STRUCTURE

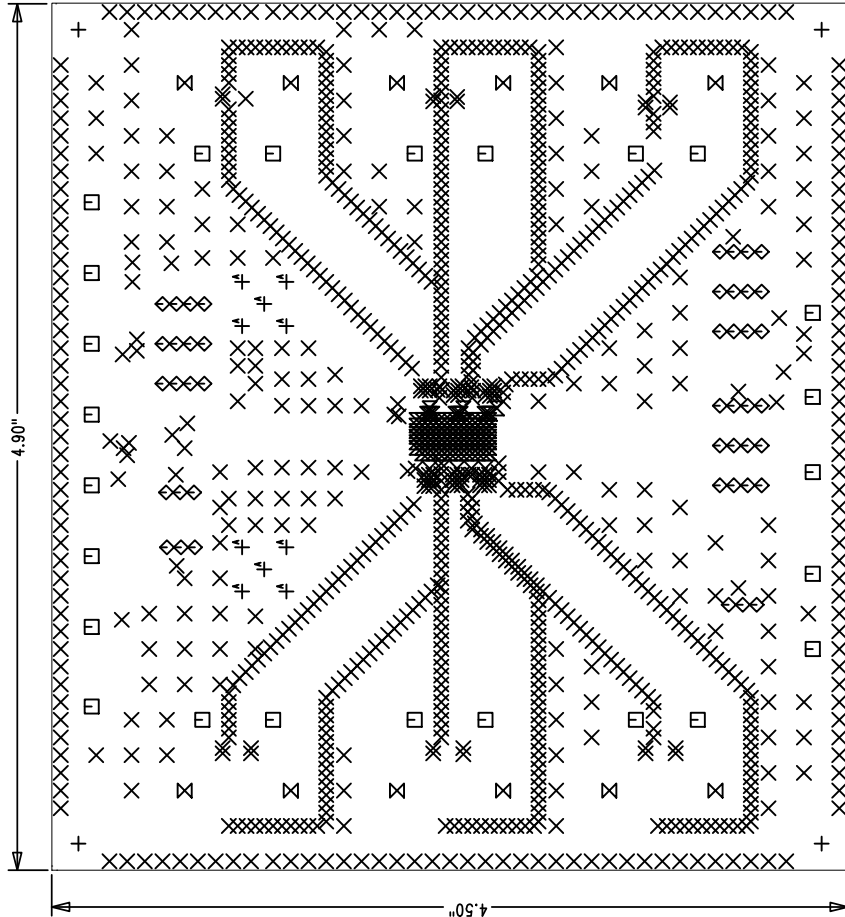


NOTES: UNLESS OTHERWISE SPECIFIED


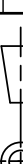
1. FAB PER IPC-A-600.
2. MATERIAL: -EPOXY FIBERGLASS; NEMA GRADE FR-4  
-FINISHED THICKNESS TO BE 0.062" +/- .005"  
-TOTAL OF 4 LAYERS WITH 2 OZ. FINISHED CU ON ALL LAYERS  
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.  
0.00" ARE PRIMARY DATUMS.
4. DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.  
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.  
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
- PLUG ALL VIA'S WITH EPOXY.  
AND PLATE OVER. PLANARIZE FINAL SURFACE.
5. FINISH: -SNOBC USING LPI BOTH SIDES, COLOR GREEN.  
-GOLD IMMERSION BOTH SIDES.  
-FOR SILKSCREEN: BOTH SIDES USE WHITE NON-CONDUCTIVE INK.
6. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.  
PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
7. PCB'S ARE TO BE RoHS COMPLIANT.
8. SCORING FOR PANELIZED PCB:



9. DESIGN HAS SOLDER MASK DEFINED PADS ON U1. U1 SOLDER MASK SIZE IS 0.4MM AND PAD SIZE IS 0.5MM. DO NOT CHANGE ANY SIZE ON THIS COMPONENT.
10. PLUG ALL VIA'S WITH COPPER AND PLATE OVER.  
PLANARIZE FINAL SURFACE.



SIZE	QTY	SYM	PLATED	TOL
0.187	4	+	NO	+/-0.003
0.01	978	X	YES	+/-0.003
0.09528	25	□	YES	+/-0.003
0.03543	45	◇	YES	+/-0.003
0.205	12	⊗	YES	+/-0.003
0.006	109	⊗	YES	+/-0.003
0.05512	10	⊕	YES	+/-0.003

UNLESS OTHERWISE SPECIFIED		APPROVALS		 www.analog.com			
DIMENSIONS ARE IN INCHES		PCB DES.	Hz	TITLE: FABRICATION DRAWING  5.5V <sub>IN</sub> , TRIPLE 3A LINEAR REGULATOR μMODULE WITH HIGH PSRR, AND AN ULTRAFAST TRANSIENT RESPONSE			
TOLERANCES:		APP ENG.	N:HARA				
0.XX = ± 0.01 0.XXX = ± 0.005 INTERPRET DIM AND TOL PER ASME Y14.5M-1994 THIRD ANGLE PROJECTION							
				SIZE	IC NO. LTM4709EY	REV	2
				N/A	DEMO CIRCUIT 3211A		
		SCALE = NONE			FILENAME:	DC3211A2.PCB	SHT 1 OF 1